

May Newsletter, 2016

http://rochester.ieee.org

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Message from the Chair

It is almost hard to believe that it is May! In April, we had our Joint Chapters Meeting featuring Barry Silverstein who spoke on technologies developed in Rochester related to the IMAX laser projection system. Several of the Chapters also had technical presentations at the meeting. I am endebted to all of the volunteers that help make this meeting a success. In particular, I would like to thank our Vice Chair Dave Krispinsky who took the



lead in running the JCM. His efforts made the meeting even more successful. One notable improvement was that a number of the technical presentations were eligibile as Professional Development Hours. Look for the Rochester Section to offer more PDH credit in the future! Thank you Dave!

As the school year comes to a close, I also wish to say goodbye to all of our great IEEE student members. This year was a fantastic year for the local IEEE student groups. I look forward to seeing you at the beginning of the next semester. Have a great summer! Dry Dlendie



3D Printing and Its Computational Challenges/Opportunities





Date: Monday, May 2 **Time**: 6:00 p.m. to 7:30 p.m. 6:00 Pizza/Networking, 6:30 Presentation Location: RIT Campus, Golisano Hall - Bldg 70, Room 1400 http://ewh.ieee.org/r1/rochester/computer Cost: Free. Open to IEEE members and non-members.

Industrial and Systems Eng., RIT

Denis Cormier, PhD The 3D Printing (3DP) industry has witnessed tremendous growth over the past decade. Much of the technology's growth stems from the fact that it allows virtually anyone to quickly

and easily turn their ideas into functional prototypes. This talk will provide a short introduction to the wide range of 3D printing technologies in use today. One of the most exciting recent developments in 3D printing involves the use of "digital materials". In the same way that color documents are produced with multiple ink or toner cartridges, multi-material 3D printed parts can be produced by locally printing blends of different materials in any desired proportion. The resulting part's material properties can therefore be optimized for a given application and need not be uniform. As exciting as multi-material 3D printing is, it opens up a number of computing challenges for part design, geometry optimization, and file preparation. This talk will describe these challenges and opportunities in the context of recent multi-material 3D printing research projects at RIT's Additive Manufacturing and Multifunctional Printing (AMPrint) Center.



Networking Meeting

WED, 11-May-2016 5:30PM to 07:30PM

Rochester PACE



Location: University of Rochester Campus, Goergen Hall - Room 109 https://meetings.vtools.ieee.org/m/20579

Cost: Free. Open to IEEE members and non-members.

Agenda

5:30 PM: Light refreshments will be served

6:00 PM: Linda Marshall, Carestream, to speak on essentials of professional networking

6:15 PM - 7:00 PM: Networking

Linda Marshall became an avid networker after taking a course in "Social Capital for Competitive Advantage" at Michigan Business School. Since then she's had 13 job offers resulting from informational interviews, meetings and networking. Four of the offers were roles created specifically for her. Linda has held various roles as project manager, quality consultant, unit director, chief system engineer, strategic planning director, assistant controller and most recently led a transformation project, moving a \$1.2B business on market trend after the merger of two value centers. She was a senior portfolio analyst in the Center of Innovation & Technology Development and loves to analyze big data. Linda has a BS in Chemical Engineering from Lehigh University, an MS in Applied & Mathematical Statistics from Rochester Institute of Technology, and an MBA from the University of Rochester Simon School. She is currently Product Development Competency Program Manager at Carestream.

Rochester Section Excom meeting

DAY: TUESDAY, 3-May-2016 TIME: 12:00PM to 1:00PM

Location: Hibachi Sushi Buffet, OfficeMax South Town Plaza, 3333 W Henrietta Rd, Rochester, NY https://meetings.vtools.ieee.org/m/37449

If you are looking for a cheap lunch (\$5 for members and \$3 for students), join us for the next monthly Rochester Section IEEE Executive Committee meeting. All current and prospective IEEE members may attend! Please join us to learn more about the Society and how you may contribute. We are always looking for new members and volunteers.

The Rochester Section welcomes the following new members: Gerard Guinta, Satish Kandlikar, Thomas Kennedy, Ahlia Kitwana, Joseph LaGoy, Christopher Smith, Alexander Sojda, Umer Usman, and Praveen Koya.













IEEE Grade Description	Members
Associate Member	14
Fellow	16
Graduate Student	83
Life Fellow	12
Life Member	94
Life Senior	33
Member	463
Senior Member	95
Student Member	52
Total	862